

An Out-of-Plane Polysilicon Actuator with a Smooth Vertical Mirror for Optical Fiber Switch Application

Makoto Mita, Daisuke Miyauchi*, Hiroshi Toshiyoshi and Hiroyuki Fujita
 Institute of Industrial Science, The University of Tokyo
 7-22-1 Roppongi, Minatoku, Tokyo 106-8558 Japan
 * Address: R&D center, TDK Corporation.
 15-7 Higashi Owada 2, Ichikawa, Chiba 272, Japan

INTRODUCTION

Micromachined optical switches are under intensive study for optical communication networks. Some of them require special high-aspect-ratio technologies such as LIGA[1] and deep RIE[2]. Some are a few millimeters in size[3,4]. We have designed a 2x2 micro optical switch which is micro-meters in size, fully micromachined except one step, and has a simple mechanism because of electrostatic actuation.

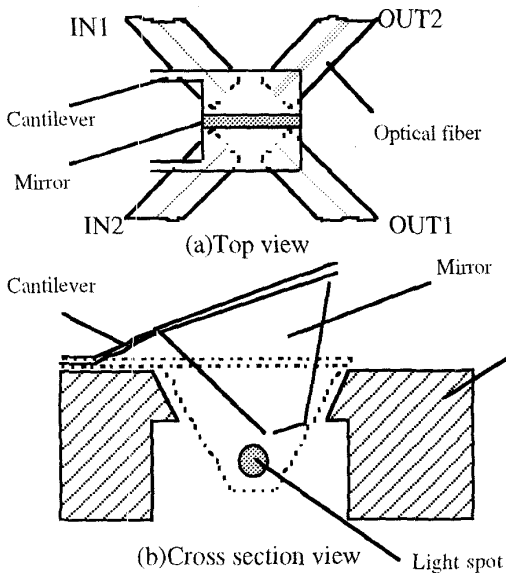


Fig.1 Device schematics

removing the electrostatic force, the plate and the mirror move up and the light beam is directly introduced to a fiber (OUT1).

removing the electrostatic force, the plate and the mirror move up and the light beam is directly introduced to a fiber (OUT1).

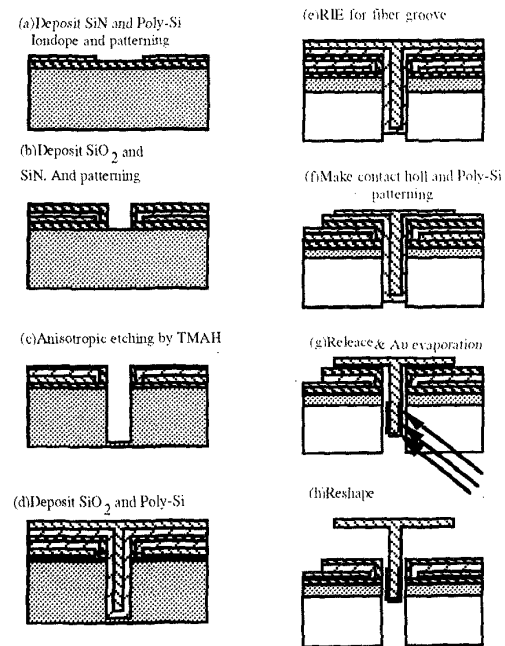


Fig.2 Proposed process flow of optical switch

The switch has following advantages:

- (1) The distance between fibers can be as close as a few tens of micrometers,
- (2) fiber alignment is assured by grooves,
- (3) the mirror can be as large as a few

hundreds of microns,
 (4) the mirror surface is smooth because it is the replica of a wet-etched (111) plane, and
 (5) fabrication can be batch processed except the final reshaping step.

TEST DEVICE

In order to confirm the concept, we have fabricated a test device.

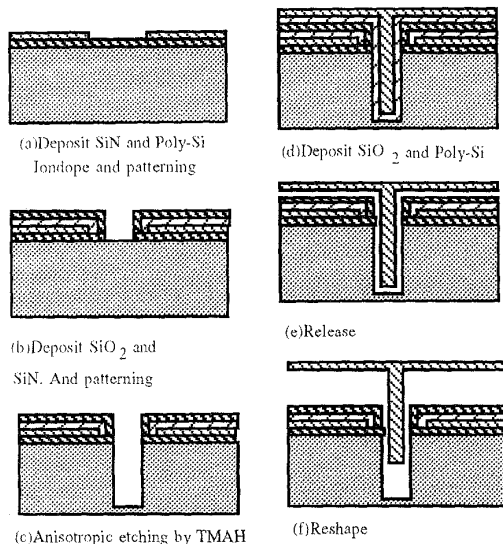
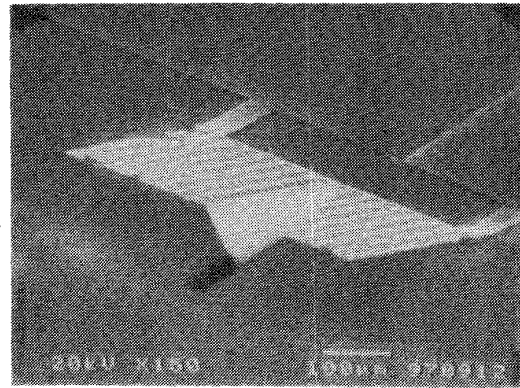


Fig.3 Process flow of the test device

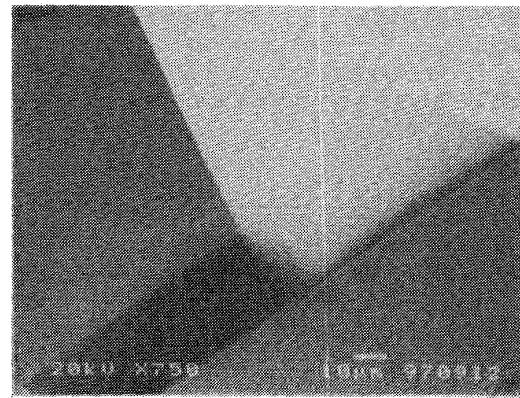
The fabrication process is shown in Fig. 3. First driving electrodes is made by LPCVD of silicon nitride (0.1 μm) and Poly-Si (1 μm) on Si(110) substrate (300 μm). Then patterning the nitride and Poly-Si by RIE. After the electrode is covered by silicon oxide(1 μm) and silicon nitride(0.1 μm), the trench is formed by anisotropic etching in TMAH solution. It is 30 μm wide, 500 micrometers long and 170 μm deep. Sacrificial silicon oxide (4 μm) and poly-Si(1 μm) are deposited by LPCVD. Then, the poly-Si is P-ion doped and patterned by RIE to form the plate and cantilevers. After etching the sacrificial oxide by HF, the plate and mirror are raised out-of plane and held there by plastic deformation. The reshaping is done with a current of 20 mA and current duration of 1 minutes.

SEM pictures are shown in Fig. 4. The plate is 500 μm square and 1 μm in thickness. Cantilevers are 400 μm in length and 50 μm in width. The height of the plate edge is 100 μm from the substrate. The characterization of the actuator is under way and will be given in the presentation. Using a simple cantilever which was reshaped, the life-time test was

carried out. We did not observe any failure even after one million cycles of bending operation with electrostatic force.



(a) Reshaped cantilever with mirror



(b) Close up view of mirror and trench

Fig.4 SEM micrograph of the test device

References

- [1] J.Mohr, et al. "Micro Optical Switching by Electrostatic Linear Actuators with Large Displacements" Proc. Transducers-93, pp.120-123
- [2] C.Marxer, et al. "Vertical Mirrors Fabricated By Reactive Ion Etching For Fiber Optical Switching Applications" Proc. MEMS-97, pp.49-54
- [3] R. A. Miller, et al. "An Electromagnetic MEMS 2x2 Fiber Optic Bypass Switch" Proc. Transducers-97, pp.89-92
- [4] Shi-Sheng Lee, et al. "Surface-Micromachined Free-Space Fiber Optic Switches With Integrated Microactuators for Optical Fiber Communication System" Proc. Transducers-97, pp.85-88
- [5] Fukuta, et al. "A RESHAPING TECHNOLOGY WITH JOULE HEAT FOR THREE DIMENSIONAL SILICON STRUCTURES" Proc. Transducers-95, pp.174-177